

July 10, 2008

To: Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Fr:

Stephen B. Ackerman, Reg. No. 37,761

28 Davis Avenue

Poughkeepsie, N.Y. 12603

Subject:

Serial No.

10/796,427

Mar. 9, 2004

MOU-SHIUNG LIN et al.

"WIREBOND PAD FOR SEMICONDUCTOR CHIP

OR WAFER"

Grp. Art Unit: 2822

LEWIS, MONICA

## RESPONSE TO FINAL OFFICE ACTION

Dear Sir:

In response to the Final Office Action mailed Jun. 11, 2008, please amend the aboveidentified application for patent and consider the remarks as follows:

## **CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on Jul. \$\mathcal{H}\$, 2008.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date \

29.2008

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Claims begin on page 4 of this paper.

Amendments to the Drawings begin on page 10 of this paper and include an attached replacement sheet.

Remarks/Arguments begin on page 11 of this paper.

An Appendix including replacement figures is attached following page 19 of this paper.